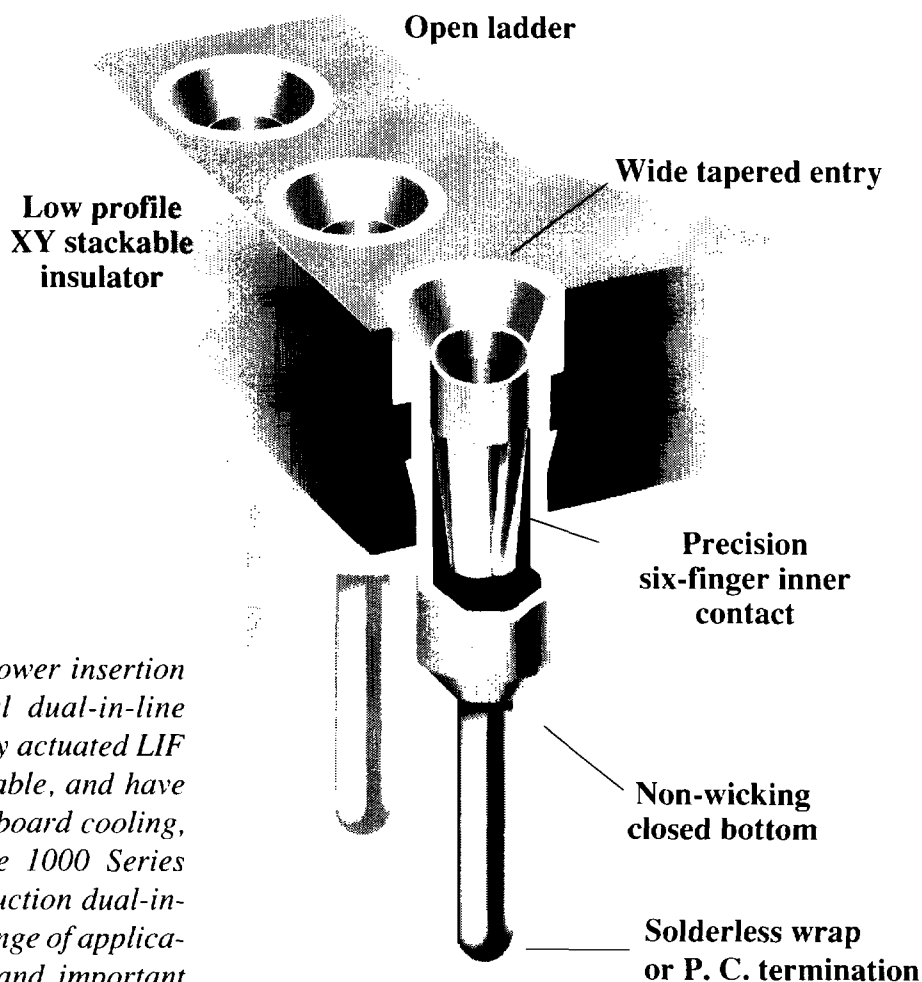
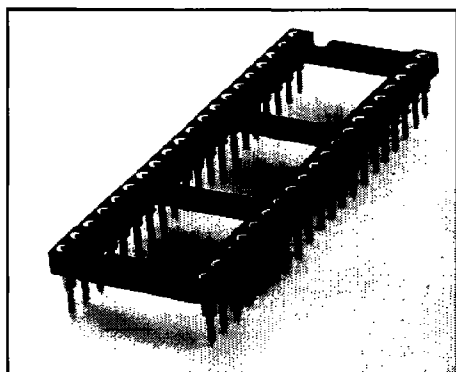
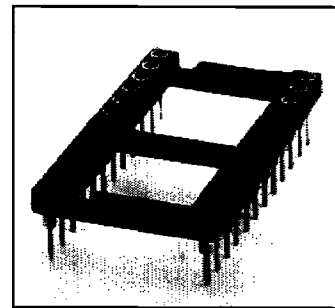


1000 Series

Six Fingered Contact Low Insertion Force DIP Sockets



The Augat 1000 Series sockets offer lower insertion force than comparable conventional dual-in-line constructions. Yet unlike mechanically actuated LIF designs, they're low profile, XY stackable, and have open ladder construction to facilitate board cooling, cleaning and inspection. So with the 1000 Series sockets, the many advantages of production dual-in-line sockets are available for a wide range of applications requiring low insertion forces and important wiping action.

- Precision six-fingered inner contacts provide concentric funnel entry for easy, safe, low insertion force DIP socketing.
- Non-wicking, closed bottom sleeve gives 100% protection against flux and solder contamination. Choice of solderless wrap or PC termination.
- Standard dual-in-line body offers greater production convenience and performance reliability than bulky, mechanically actuated LIF designs. Low profile. XY stackable. Open ladder for cooling, cleaning and inspection. Applications from 8 to 64 positions.
-  Underwriters Laboratories, Inc. approval pending

1000 Series

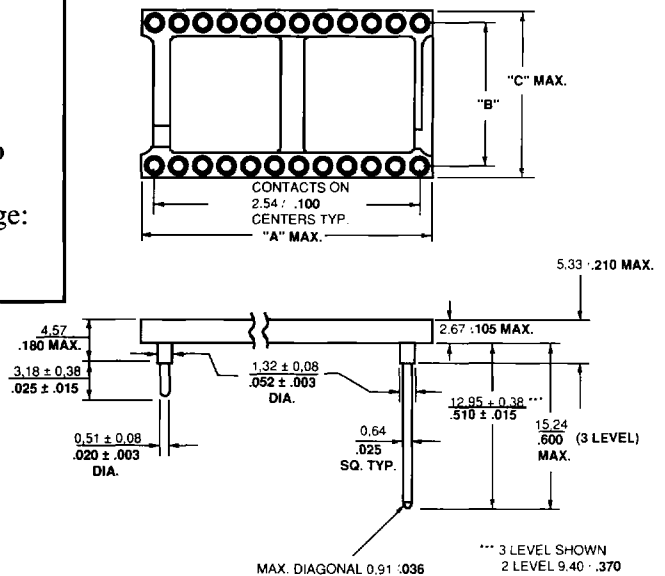
STANDARD CONFIGURATIONS

NO. OF CONTACTS	A	B $\pm \begin{smallmatrix} 0.13 \\ .005 \end{smallmatrix}$	C
8	$\frac{10.16}{.400}$	7.62 .300	$\frac{10.16}{.400}$
14	$\frac{17.78}{.700}$		
16	$\frac{20.32}{.800}$		
18	$\frac{22.86}{.900}$		
20	$\frac{25.40}{1.000}$		
22	$\frac{27.94}{1.100}$	$\frac{10.16}{.400}$	$\frac{12.70}{.500}$
24**	$\frac{30.40}{1.200}$	$\frac{7.62}{.300}$	$\frac{10.16}{.400}$
24*		$\frac{10.16}{.400}$	$\frac{12.70}{.500}$
24		15.24 .600	$\frac{17.78}{.700}$
28	$\frac{35.36}{1.400}$		
32	$\frac{40.64}{1.600}$		
36	$\frac{45.72}{1.800}$		
40	$\frac{50.80}{2.000}$		
42	$\frac{53.34}{2.100}$		
48	$\frac{60.96}{2.400}$		
64	$\frac{81.28}{3.200}$	$\frac{22.86}{.900}$	$\frac{25.40}{1.000}$

APPLICATION DIMENSIONS

- PCB Thickness Range:
Standard .062" and .092"
- PCB Hole Size Range:
.035" $\pm$.003" Solder
Termination, .055" $\pm$.0015" Solderless Wrap
- IC Pin Dimension Range:
.016" to .021" Dia.
.115" Min. Length

DIMENSIONS mm/in



MATERIAL SPECIFICATIONS

INSULATOR	Thermoplastic Polyester Rated 94V-0
OUTER SLEEVE	Machined Brass/Formed Copper, Tin/Lead, or Gold Plated
INNER CONTACTS ...	Stamped Beryllium- Copper, 30 μ " Gold over Nickel

PART NUMBER EXAMPLE (1028-AG11D)

1 0 X X - A G X X X

1000
SERIES

NUMBER OF
CONTACTS (8—64)
(See chart for standard
configurations)

D PC Termination
(.125" or .180")
F 3-Level Solder-
less Wrap
F-2 2-Level Solder-
less Wrap

NOTES:

- ** Use only to designate 24 Position .300 Centerline
- * Use only to designate 24 Position .400 Centerline

PERFORMANCE CHARACTERISTICS

Stamped Low Force Contactpg. H8

TERMINATION	NOTES	XX	CONTACT PLATING	SLEEVE PLATING
D(.125"), F & F-2		10	Gold	Gold
		11	Gold	Tin/Lead
	**	30	Gold	Gold
	**	31	Gold	Tin/Lead
	*	40	Gold	Gold
	*	41	Gold	Tin/Lead
D(.180")		45	Gold	Gold
		44	Gold	Tin/Lead